

MBRB3030CT

Preferred Device

SWITCHMODE™ Power Rectifier

Using the Schottky Barrier principle with a proprietary barrier metal. These state-of-the-art devices have the following features:

- Guardring for Stress Protection
- Maximum Die Size
- 150°C Operating Junction Temperature
- Short Heat Sink Tab Manufactured - Not Sheared

Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL94, VO
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units per Plastic Tube
- Available in 24 mm Tape and Reel, 800 Units per 13" Reel by Adding a "T4" Suffix to the Part Number
- Marking: B3030
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)
Human Body Model, 3B (>8000 V)

MAXIMUM RATINGS

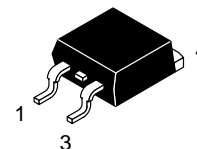
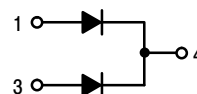
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	30	V
Average Rectified Forward Current (At Rated V_R , $T_C = 134^\circ\text{C}$) Per Device Per Leg	$I_{F(AV)}$	30 15	A
Peak Repetitive Forward Current (At Rated V_R , Square Wave, 20 kHz, $T_C = +137^\circ\text{C}$) Per Leg	I_{FRM}	30	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I_{FSM}	200	A
Peak Repetitive Reverse Surge Current (2.0 μs , 1.0 kHz)	I_{RRM}	2.0	A
Storage Temperature Range	T_{stg}	-55 to +150	°C
Operating Junction Temperature	T_J	-55 to +150	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs
Reverse Energy (Unclamped Inductive Surge) (Inductance = 3 mH, $T_C = 25^\circ\text{C}$)	W	100	mJ



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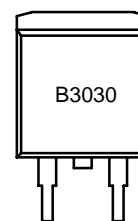
<http://onsemi.com>

SCHOTTKY BARRIER RECTIFIER 30 AMPERES 30 VOLTS



D²PAK
CASE 418B
STYLE 3

MARKING DIAGRAM



B3030 = Device Code

ORDERING INFORMATION

Device	Package	Shipping
MBRB3030CT	D ² PAK	50/Rail
MBRB3030CTT4	D ² PAK	800/Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

MBRB3030CT

THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance — Junction to Case	$R_{\theta JC}$	1.0	$^{\circ}C/W$
— Junction to Ambient (Note 1.)	$R_{\theta JA}$	50	

ELECTRICAL CHARACTERISTICS (Per Leg)

Maximum Instantaneous Forward Voltage (Note 2.), Per Leg ($I_F = 15$ Amps, $T_C = +25^{\circ}C$) ($I_F = 15$ Amps, $T_C = +150^{\circ}C$) ($I_F = 30$ Amps, $T_C = +25^{\circ}C$) ($I_F = 30$ Amps, $T_C = +150^{\circ}C$)	V_F	0.54 0.47 0.67 0.66	Volts
Maximum Instantaneous Reverse Current (Note 2.), Per Leg (Rated dc Voltage, $T_C = +25^{\circ}C$) (Reverse Voltage = 10 V, $T_C = +150^{\circ}C$) (Rated dc Voltage, $T_C = +150^{\circ}C$)	I_R	0.6 46 145	mA

1. When mounted using minimum recommended pad size on FR-4 board.
2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

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ELECTRICAL CHARACTERISTICS

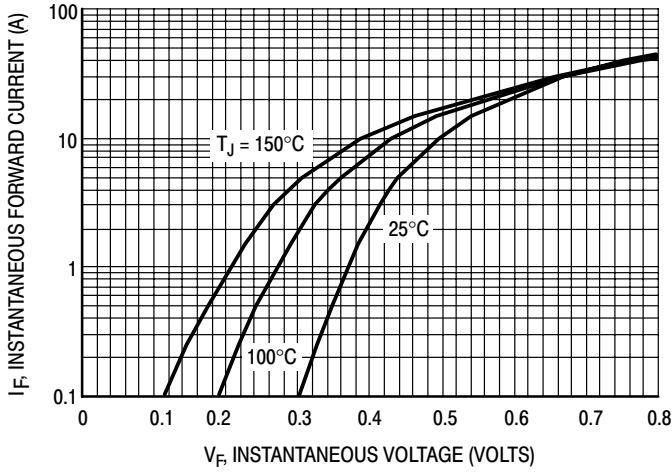


Figure 1. Maximum Forward Voltage, Per Leg

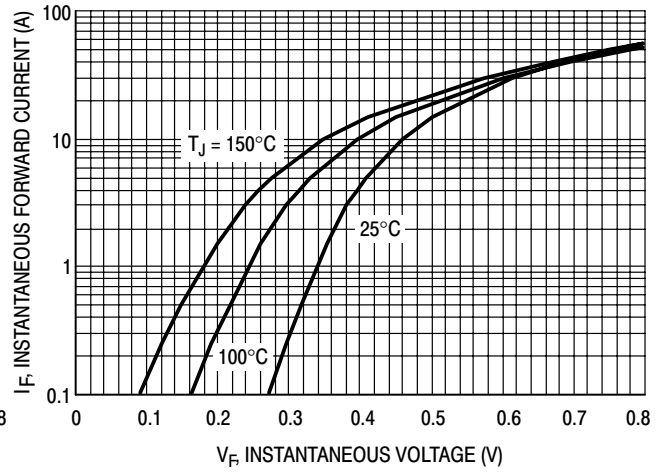


Figure 2. Typical Forward Voltage, Per Leg

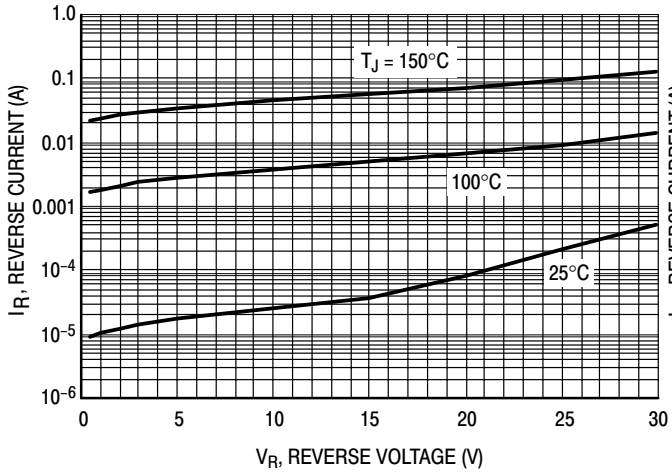


Figure 3. Maximum Reverse Current, Per Leg

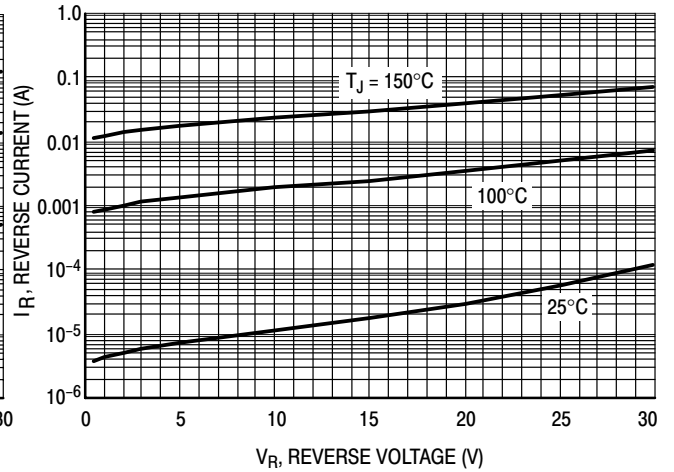


Figure 4. Typical Reverse Current, Per Leg

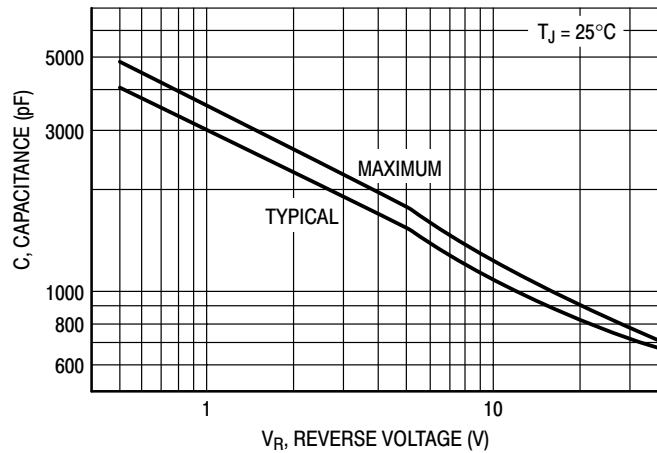


Figure 5. Capacitance

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TYPICAL CHARACTERISTICS

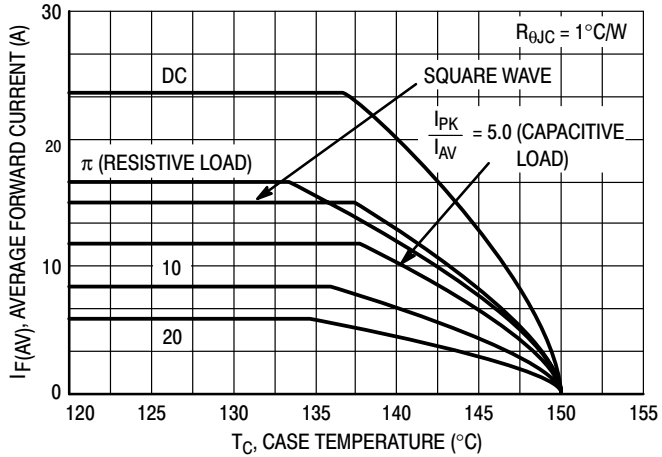


Figure 6. Current Derating, Infinite Heatsink

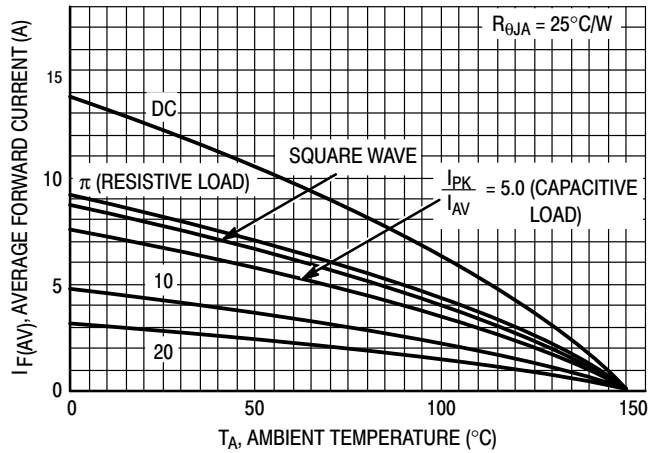


Figure 7. Current Derating

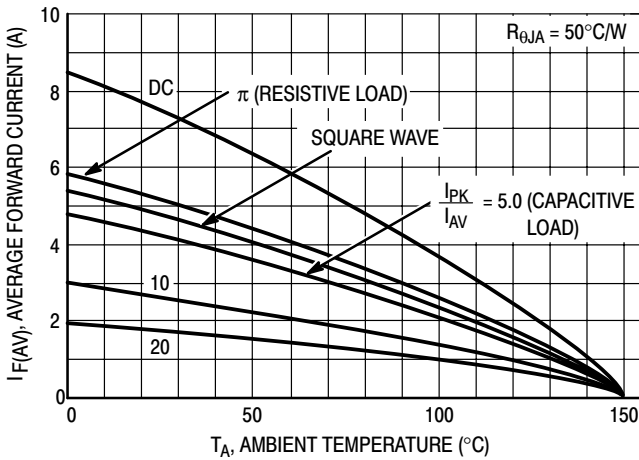


Figure 8. Current Derating, Free Air

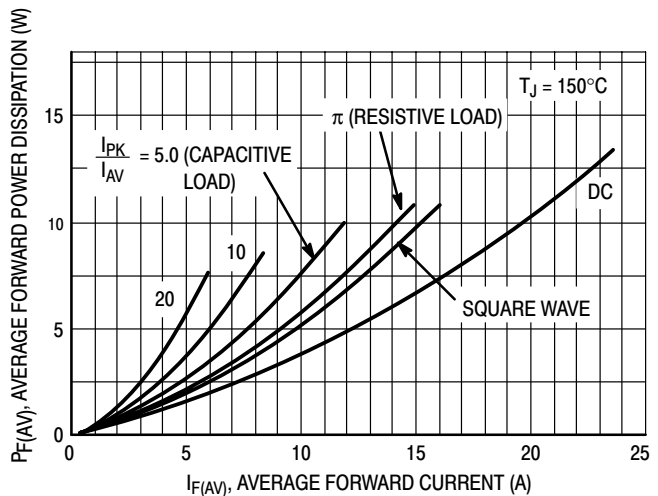


Figure 9. Forward Power Dissipation

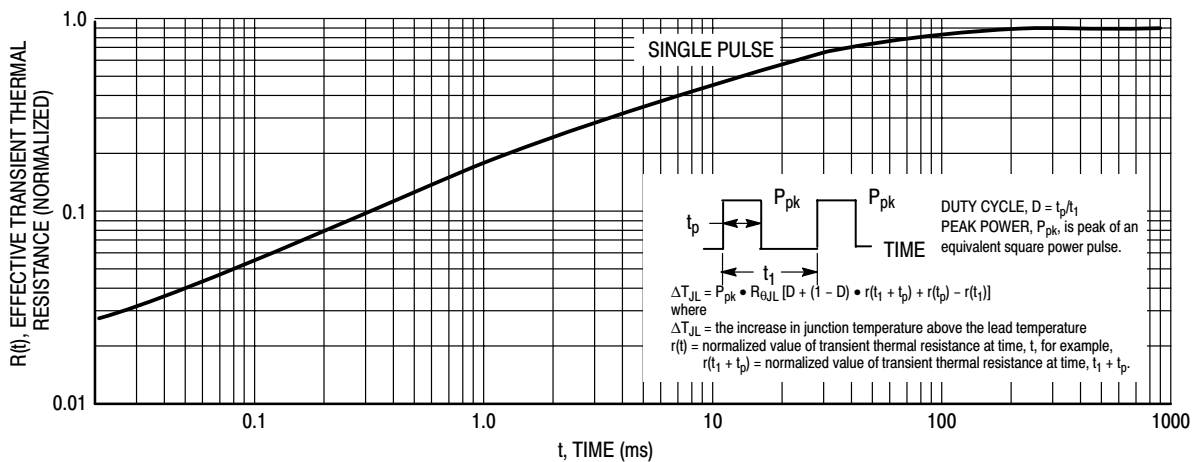


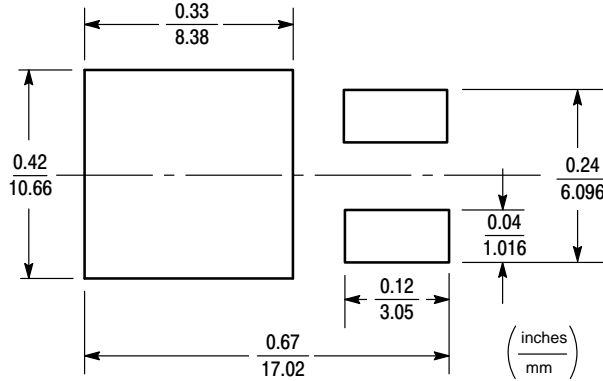
Figure 10. Thermal Response

INFORMATION FOR USING THE D²PAK SURFACE MOUNT PACKAGE

MINIMUM RECOMMENDED FOOTPRINTS FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection

interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



D²PAK POWER DISSIPATION

The power dissipation of the D²PAK is a function of the drain pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient; and the operating temperature, T_A . Using the values provided on the data sheet for the D²PAK package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values

into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 2.5 watts.

$$P_D = \frac{150^\circ\text{C} - 25^\circ\text{C}}{50^\circ\text{C/W}} = 2.5 \text{ watts}$$

The 50°C/W for the D²PAK package assumes the recommended drain pad area of 158K mil² on FR-4 glass epoxy printed circuit board to achieve a power dissipation of 2.5 watts using the footprint shown. Another alternative is to use a ceramic substrate or an aluminum core board such as Thermal Clad™. By using an aluminum core board material such as Thermal Clad, the power dissipation can be doubled using the same footprint.

GENERAL SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 5 seconds.

- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling

* * Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

* * Due to shadowing and the inability to set the wave height to incorporate other surface mount components, the D²PAK is not recommended for wave soldering.

RECOMMENDED PROFILE FOR REFLOW SOLDERING

For any given circuit board, there will be a group of control settings that will give the desired heat pattern. The operator must set temperatures for several heating zones, and a figure for belt speed. Taken together, these control settings make up a heating “profile” for that particular circuit board. On machines controlled by a computer, the computer remembers these profiles from one operating session to the next. Figure 11 shows a typical heating profile for use when soldering the D²PAK to a printed circuit board. This profile will vary among soldering systems but it is a good starting point. Factors that can affect the profile include the type of soldering system in use, density and types of components on the board, type of solder used, and the type of board or substrate material being used. This profile shows temperature versus time.

The line on the graph shows the actual temperature that might be experienced on the surface of a test board at or near a central solder joint. The two profiles are based on a high density and a low density board. The Vitronics SMD310 convection/infrared reflow soldering system was used to generate this profile. The type of solder used was 62/36/2 Tin Lead Silver with a melting point between 177-189 °C. When this type of furnace is used for solder reflow work, the circuit boards and solder joints tend to heat first. The components on the board are then heated by conduction. The circuit board, because it has a large surface area, absorbs the thermal energy more efficiently, then distributes this energy to the components. Because of this effect, the main body of a component may be up to 30 degrees cooler than the adjacent solder joints.

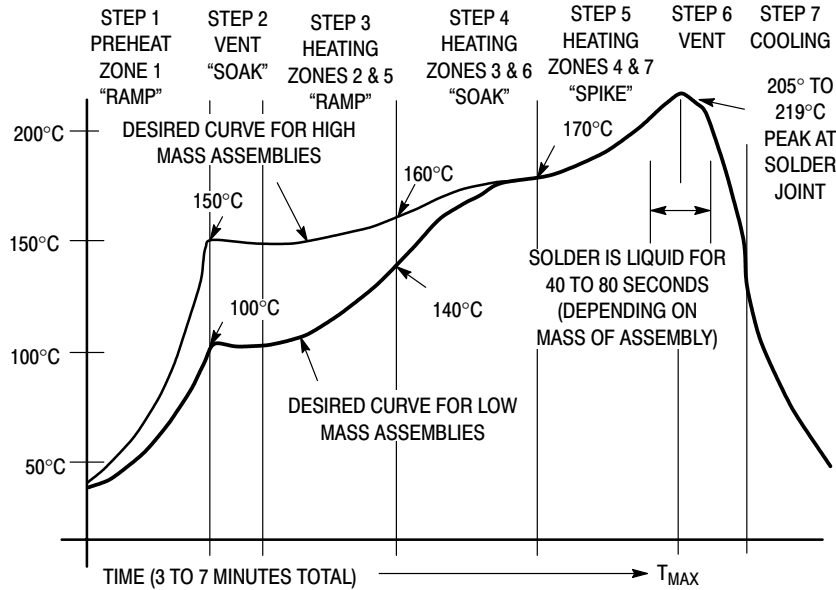
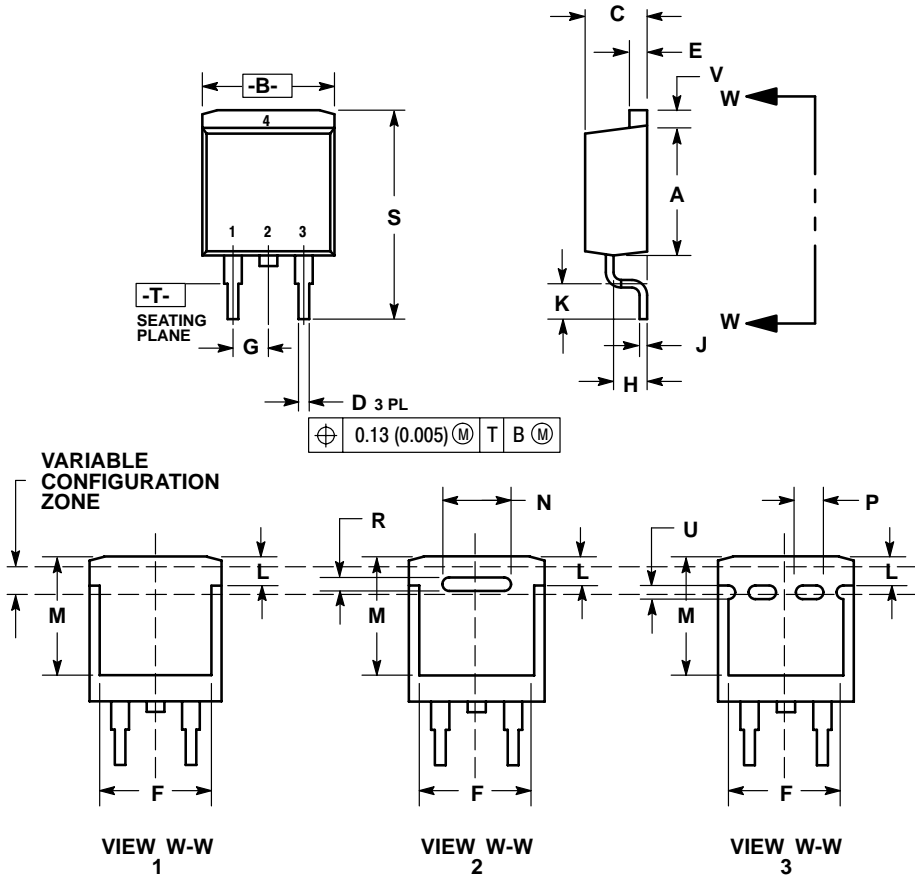


Figure 11. Typical Solder Heating Profile

MBRB3030CT

PACKAGE DIMENSIONS

D²PAK
CASE 418B-04
ISSUE H




- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

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